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In the Claims

Claims 1-16. (Canceled)

17. (Currently Amended) A method of fabricating and activating a chip-level optical transceiver comprising steps of:

providing an optical fiber;

providing a bench that supports a chip-level optical transceiver;

placing the bench in front of the optical fiber;

activating the chip-level optical transceiver; and

tilting the bench until the chip-level optical transceiver is aligned with the optical fiber and an optical signal is achieved, the chip-level optical transceiver comprising:

a light emitting device, having an output, for emitting a first wavelength of light along a first

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optical path;

a first photodiode for controlling the output of
the light emitting device;

a second photodiode having an active region;

a lens for receiving the first wavelength of light
along the first optical path from the light emitting
device and collimating the first wavelength of light to
the second photodiode along the first optical path; and

the second photodiode for reflecting the first
wavelength of light along the first optical path into
the optical fiber along a second optical path.

18. (Original) The method of claim 17, further comprising mounting the optical fiber, the bench, and the chip-level optical transceiver carried by the bench in a package.

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19. (Original) The method of claim 18, the package comprising:

a support structure securing the fiber;

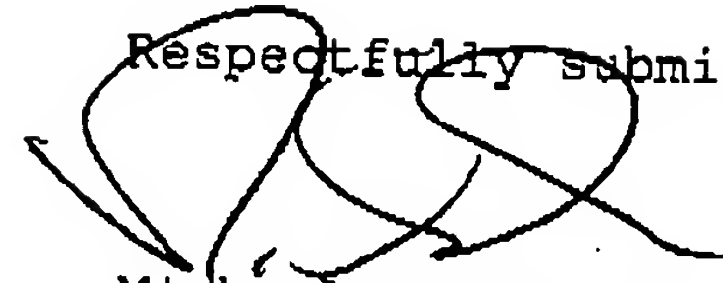
a header coupled to the support structure; and

the bench carried by the header in front of the optical fiber.

20. (Canceled)

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Respectfully submitted,



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